

RELIABILITY REPORT
FOR
MAX5200AEUB+
PLASTIC ENCAPSULATED DEVICES

August 4, 2009

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX5200AEUB+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX5200-MAX5203 serial input, voltage-output, 16-bit digital-to-analog converters (DACs) provide monotonic 16-bit output over temperature without any adjustments. The MAX5200/MAX5201 operate from a +5V single power supply featuring a +2.5V internal reference and an internal gain of 2, while the MAX5202/MAX5203 operate from a +3V or +3.3V single power supply featuring a +1.5V internal reference and an internal gain of 2. The MAX5200-MAX5203 DAC output range is typically 0 to VDD. The MAX5200-MAX5203 feature a hardware reset input (active-low CLR) that, when pulled low, clears the output to zero code 0000 hex (MAX5201/MAX5203) or resets the output to midscale code 8000 hex (MAX5200/MAX5202). The 3-wire serial interface is SPI(tm)/QSPI(tm)/MICROWIRE(tm) compatible. All devices have a low-power shutdown mode that reduces the supply current consumption to 1µA. The MAX5200-MAX5203 are available in a space-saving 10-pin µMAX® package and are guaranteed over the extended temperature range (-40°C to +105°C). Refer to the MAX5204-MAX5207 data sheet for external reference versions.

II. Manufacturing Information

A. Description/Function:	Low-Cost, Voltage-Output, 16-Bit DACs with Internal Reference in μ MAX
B. Process:	C6Y
C. Number of Device Transistors:	10547
D. Fabrication Location:	Japan
E. Assembly Location:	Philippines, Malaysia, Thailand
F. Date of Initial Production:	October 26, 2002

III. Packaging Information

A. Package Type:	10-pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0152
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	180°C/W
K. Single Layer Theta Jc:	41.9°C/W
L. Multi Layer Theta Ja:	113.1°C/W
M. Multi Layer Theta Jc:	41.9°C/W

IV. Die Information

A. Dimensions:	62 X 87 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 45 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 23.9 \times 10^{-9}$$

$\lambda = 23.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the C6Y Process results in a FIT Rate of 0.82 @ 25C and 14.21 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The DA95 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX5200AEUB+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data